Solder Alloy No.30 Grade 62S 62/36/2 Sn/Pb/Ag

DESCRIPTION

A common application of Solder Alloy No.30 is making permanent but reversible connections between copper pipes in plumbing systems. The greater the tin concentration, the greater the solders tensile and shear strengths. Common in electronics Solder Alloy No.30 is the strongest tin-lead solder. It has an appearance identical to Sn60Pb40 or Sn63Pb37. Crystals of Ag3Sn may be seen growing from the solder. Extended heat treatment leads to formation of crystals of binary alloys. The silver content decreases solubility of silver, making the alloy suitable for soldering silver-metallised surfaces, e.g. SMD capacitors and other silver-metallised ceramics. Not recommended for gold. General-purpose solder, low melting solder. Tin Lead Silver Alloy specified as Grade 62S to BS219 and No.30 to BSEN29453. Commonly known as Fry's F270 or LMP alloy. Available in tinman sticks, blow pipe and bars.

PHYSICAL PROPERTIES

Melting Point, °C Solidus/liquidus 178/190

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